

General Description

GL740A4 the silicon N-channel Enhanced VDMOSFETS, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-252, which accords with the RoHS standard.

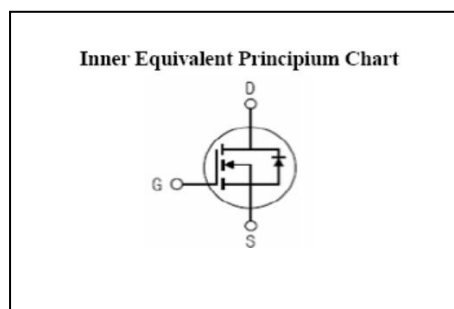
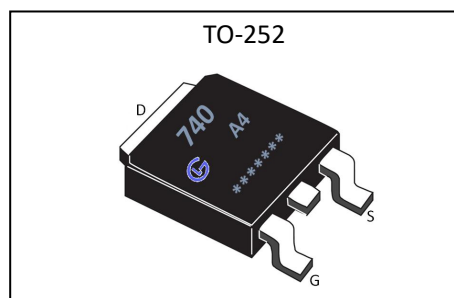
V_{DSS}	400	V
I_D	10	A
$P_D (T_C=25^{\circ}C)$	95	W
$R_{DS(ON)type}$	0.37	Ω

Features

- Fast Switching
- Low Gate Charge and $R_{DS(on)}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications

- Power switch circuit of adaptor and charger.



Absolute (Tc=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	400	V
I_D	Continuous Drain Current	10	A
	Continuous Drain Current $T_C = 100^{\circ}C$	8	A
I_{DM}^{a1}	Pulsed Drain Current	40	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}^{a2}	Single Pulse Avalanche Energy	750	mJ
E_{AR}^{a1}	Avalanche Energy ,Repetitive	70	mJ
I_{AR}^{a1}	Avalanche Current	3.5	A
dv/dt^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	95	W
	Derating Factor above 25°C	0.67	W/°C
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
T_L	Maximum Temperature for Soldering	300	°C

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device



GL740A4

GL Silicon N-Channel Power MOSFET

Electrical Characteristics (Tc=25°C unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	400	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=250\mu A$, Reference 25°C	--	0.67	--	V/°C
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=400V, V_{GS}=0V, T_a=25^\circ C$	--	--	1	μA
		$V_{DS}=320V, V_{GS}=0V, T_a=125^\circ C$	--	--	100	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+30V$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-30V$	--	--	100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=5A$	--	--	0.48	Ω
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	3.0	4.0	V
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=15V, I_D=4A$	--	9	--	S
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=25V$ $f=1.0MHz$	--	1150	--	pF
C_{oss}	Output Capacitance		--	90	--	
C_{rss}	Reverse Transfer Capacitance		--	11	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=10.0A, V_{DD}=200V$ $V_{GS}=10V, R_G=9.1\Omega$	--	11	--	ns
t_r	Rise Time		--	21	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	36	--	
t_f	Fall Time		--	20	--	
Q_g	Total Gate Charge	$I_D=10.0A, V_{DD}=200V$ $V_{GS}=10V$	--	25	--	nC
Q_{gs}	Gate to Source Charge		--	6	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	9	--	

Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	10	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	40	A
V_{SD}	Diode Forward Voltage	$I_S=10A, V_{GS}=0V$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$I_S=10A, T_j = 25^\circ C$	--	280	--	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt=100A/us, V_{GS}=0V$	--	1.2	--	uC

Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$

Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JC}$	Junction-to-Case	1.32	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient	62	$^\circ C/W$

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: $L=10.0mH, I_D=12.0A$, Start $T_j=25^\circ C$

^{a3}: $I_{SD}=10.0A, di/dt \leq 100A/us, V_{DD} \leq BV_{DS}$, Start $T_j=25^\circ C$

Test Circuits

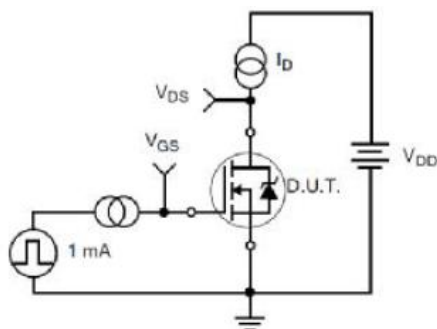


Figure 17. Gate Charge Test Circuit

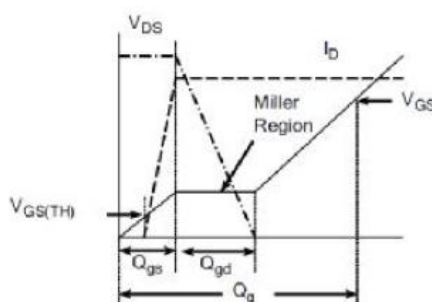


Figure 18. Gate Charge Waveform

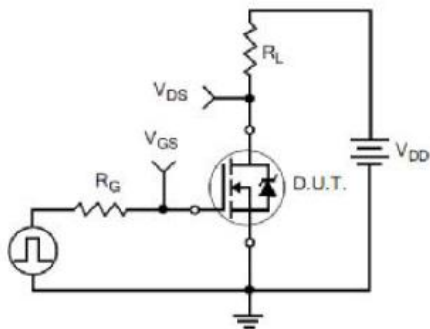


Figure 19. Resistive Switching Test Circuit

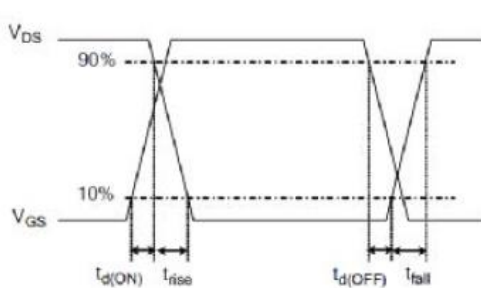


Figure 20. Resistive Switching Waveforms

Characteristics Curves

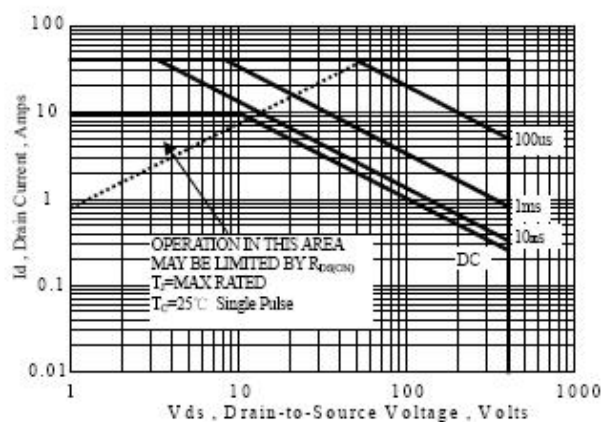


Figure 1 Maximum Forward Bias Safe Operating Area

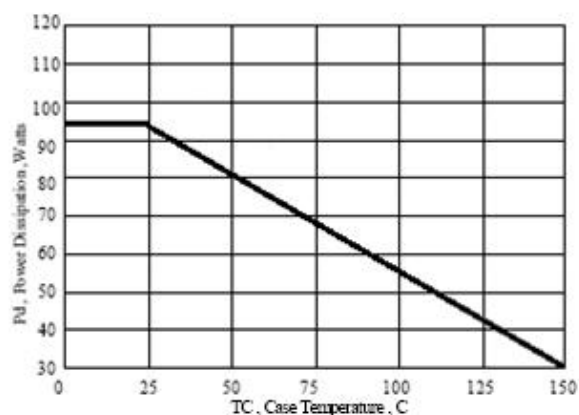


Figure 2 Maximum Power Dissipation vs Case Temperature

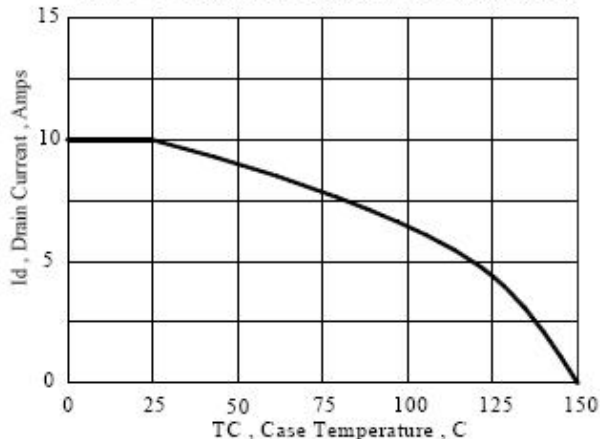


Figure 3 Maximum Continuous Drain Current vs Case Temperature

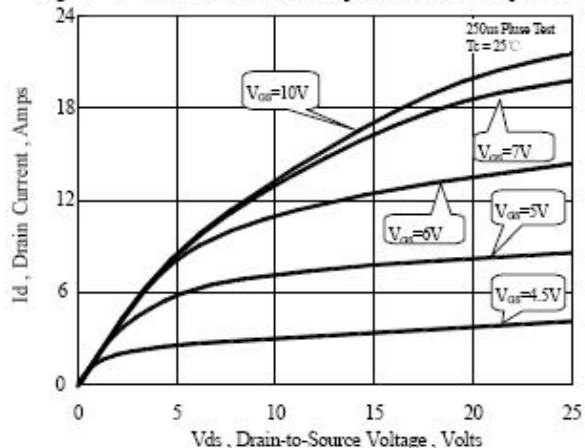


Figure 4 Typical Output Characteristics

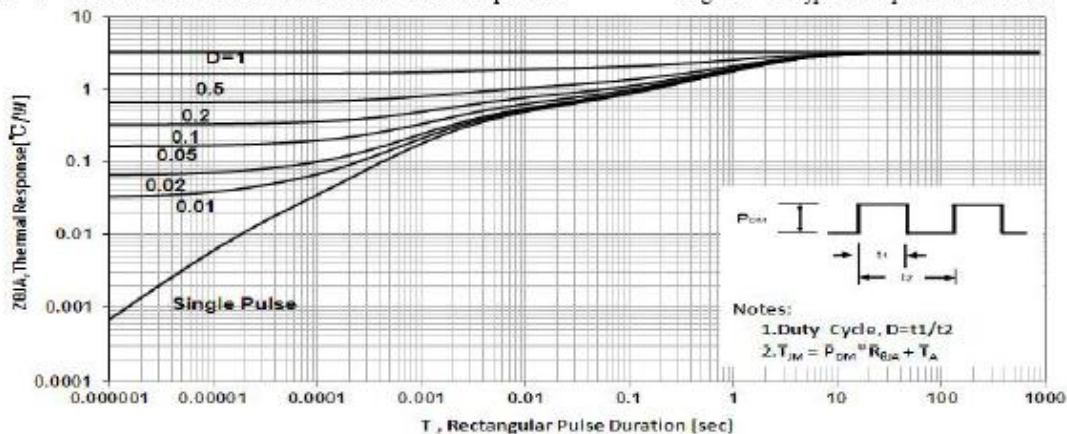


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

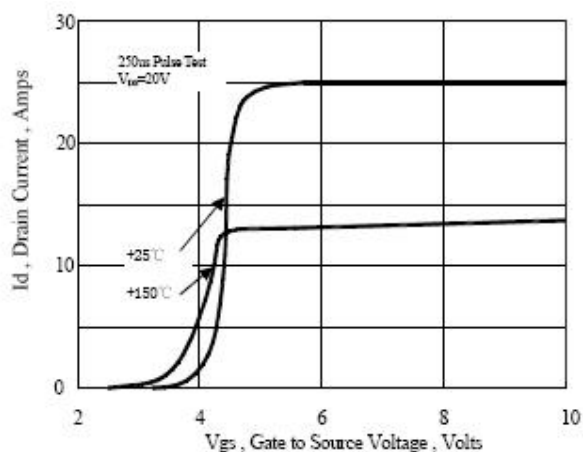


Figure 6 Typical Transfer Characteristics

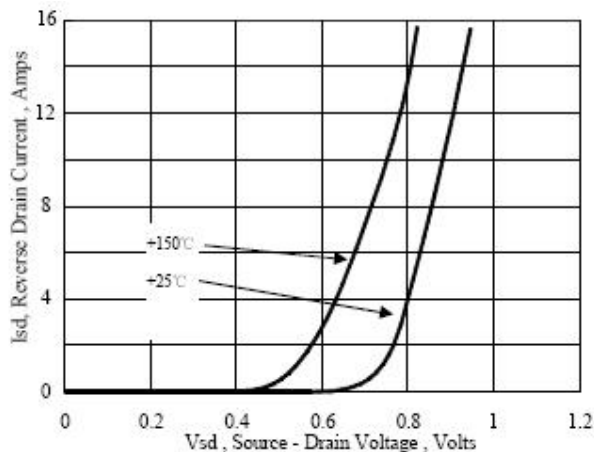


Figure 7 Typical Body Diode Transfer Characteristics

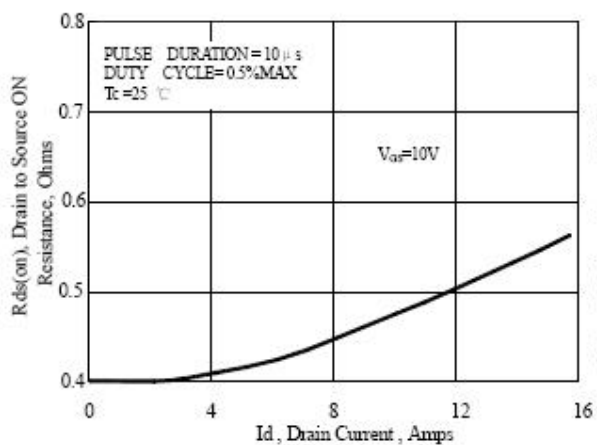


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

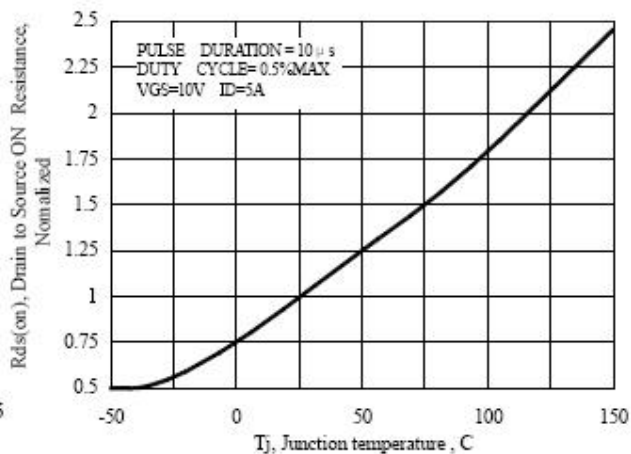


Figure 9 Typical Drain to Source on Resistance vs Junction Temperature

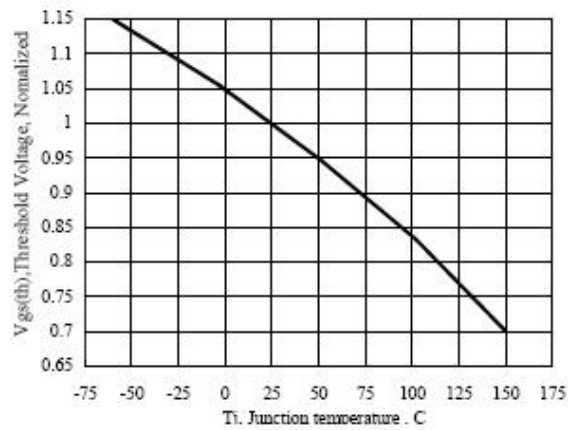


Figure 10 Typical Theshold Voltage vs Junction Temperature

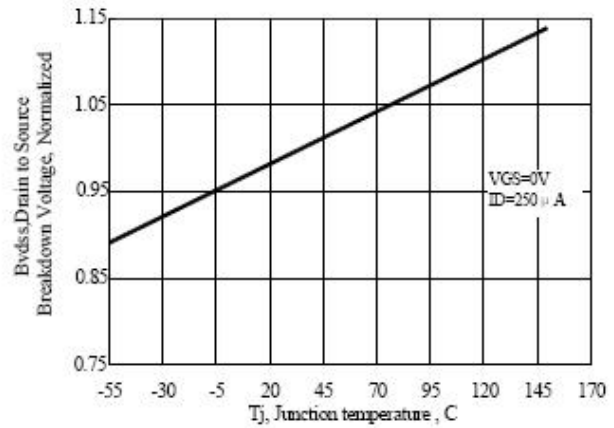


Figure 11 Typical Breakdown Voltage vs Junction Temperature

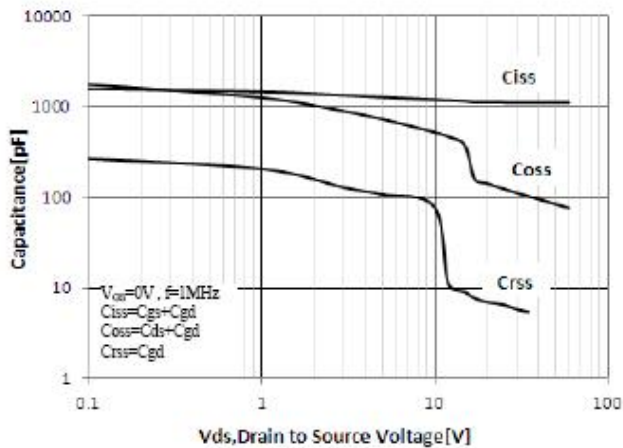


Figure 12 Typical Capacitance vs Drain to Source Voltage

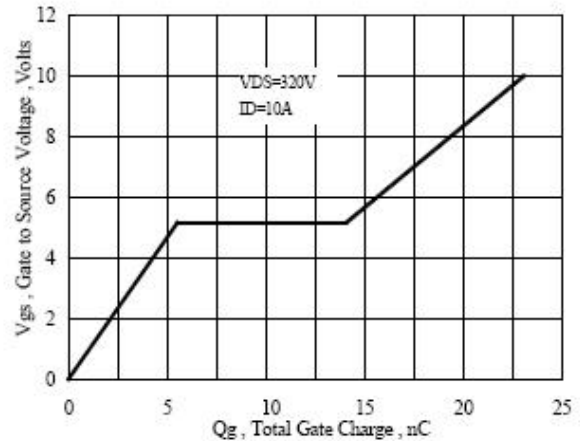


Figure 13 Typical Gate Charge vs Gate to Source Voltage